

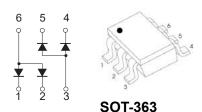


Product data sheet

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MAKING: KJC



FEATURES

- Fast Switching Speed
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance



Maximum Ratings @Ta=25°C

Parameter	Symbol	Limit	Unit
Peak Repetitive Peak Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	75	V
Forward Continuous Current	I _{FM}	300	mA
Average Rectified Output Current	Ι _Ο	150	mA
Non-Repetitive Peak Forward Surge Current @ t=8.3ms	I _{FSM}	2	А
Power Dissipation	PD	200	mW
Thermal Resistance From Junction to Ambient	$R_{\theta JA}$	625	°C/W
Operating Junction Temperature	TJ	150	°C
Storage Temperature	T _{STG}	-55~+150	°C

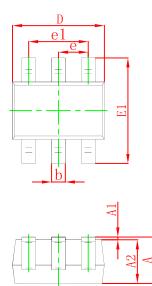
ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

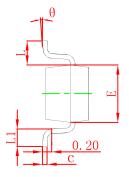
Parameter	Symbol	Test conditions	Min	Мах	Unit
Reverse breakdown voltage	V _(BR)	Ι _R = 2.5μΑ	75		V
Reverse voltage leakage current	I _R	V _R =75V V _R =20V		2.5 0.025	μA
Forward voltage	V _F	I _F =1mA I _F =10mA I _F =50mA I _F =150mA		715 855 1000 1250	mV
Capacitance between terminals	CT	V _R =0, f=1MHz		2	pF
Reveres recovery time	t _{rr}	$I_F=I_R=10mA, I_{rr}=0.1 \times I_{R}$ $R_L=100\Omega$		4	ns





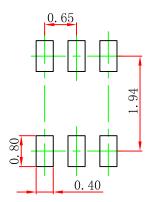
SOT-363 Package Outline Dimensions





Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
А	0.900	1.100	0.035	0.043	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.000	0.035	0.039	
b	0.150	0.350	0.006	0.014	
С	0.100	0.150	0.004	0.006	
D	2.000	2.200	0.079	0.087	
E	1.150	1.350	0.045	0.053	
E1	2.150	2.400	0.085	0.094	
e	0.650 TYP		0.026 TYP		
e1	1.200	1.400	0.047	0.055	
L	0.525 REF		0.021 REF		
L1	0.260	0.460	0.010	0.018	
θ	0°	8°	0°	8°	

SOT-363 Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:±0.05mm.

3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAW56DW	SOT-363	3000





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